Docket No.: 005957 USA/Consilium/Consilium PATENT/**OFFICIAL**

OIPE JC60 AUG 11 2004 PATENT & TRADEMARK OFFICE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	
	:	
Huey-Shin YUAN et al.	:	
	:	
Serial No. 09/811,667	:	Group Art Unit: 2163
	:	
Filed: March 20, 2001	:	Examiner:

For: FAULT TOLERANT AND AUTOMATED COMPUTER SOFTWARE WORKFLOW

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

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Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right

to present to the Office the relevant facts and law regarding the appropriate status of such document.

No certification or fee is believed to be required. However, the Commissioner is hereby authorized to charge any additional fees should any be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

Wilmer Cutler Pickering Hale and Dorr LLP



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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)

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005957 USA/ Consilium/Consilium	09/811,66
APPLICANT: Huey-Shin YUAN et al.	
FILING DATE: March 20, 2001	GROUP: 2163

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